

**4-PIN SOP, 2.2  $\Omega$  LOW ON-STATE RESISTANCE  
1-ch Optical Coupled MOS FET****DESCRIPTION**

The PS7200H-1A is a low on-state capacitance solid state relay containing a GaAs LED on the light emitting side (input side) and MOS FETs on the output side.

It is suitable for high-frequency signal control, due to its low  $C \times R$ , low on-state resistance, and low off-state leakage current.

**FEATURES**

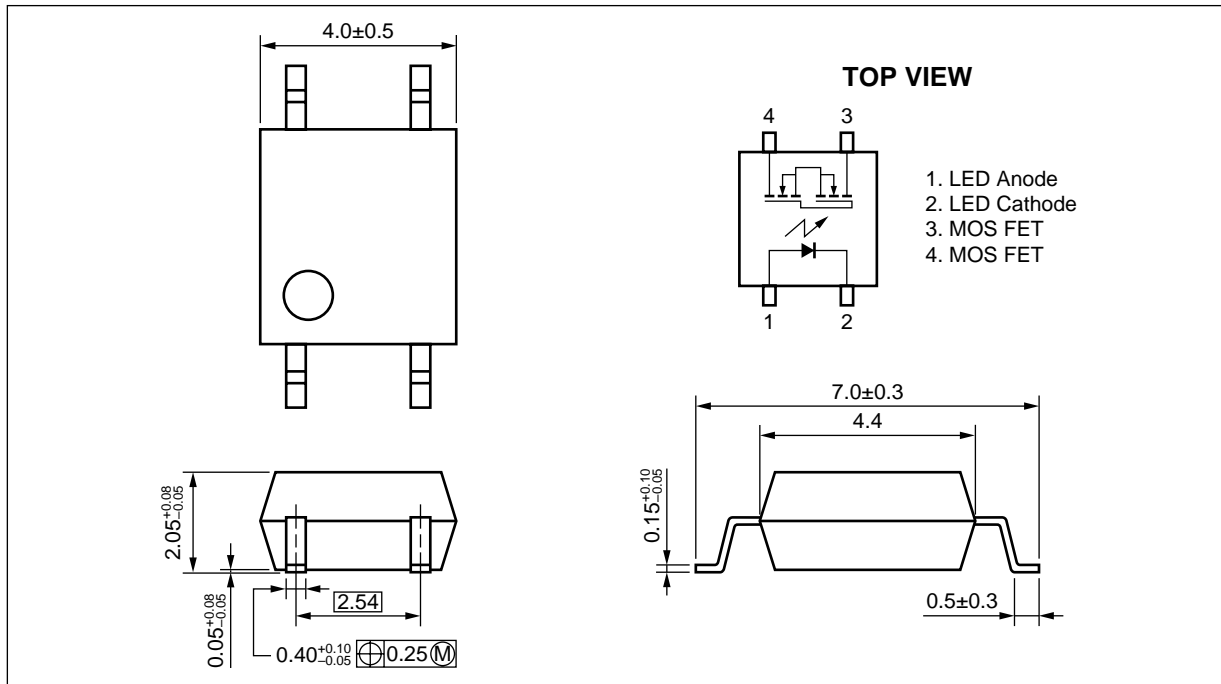
- Low  $C \times R$  ( $C \times R = 9.2 \text{ pF} \cdot \Omega$ )
- Low on-state resistance ( $R_{\text{on}} = 2.2 \Omega$  TYP.)
- Low output capacitance ( $C_{\text{out}} = 4.2 \text{ pF}$  TYP.)
- Low off-state leakage current ( $I_{\text{off}} = 0.03 \text{ nA}$  TYP.)
- High-speed turn-on time ( $t_{\text{on}} = 0.04 \text{ ms}$  TYP.)
- 1 channel type (1 a output)
- Designed for AC/DC switching line changer
- Small and thin package (4-pin SOP, Height = 2.1 mm)
- High isolation voltage ( $BV = 1\,500 \text{ Vr.m.s.}$ )
- Low offset voltage
- Ordering number of taping product: PS7200H-1A-E3, E4, F3, F4

**APPLICATIONS**

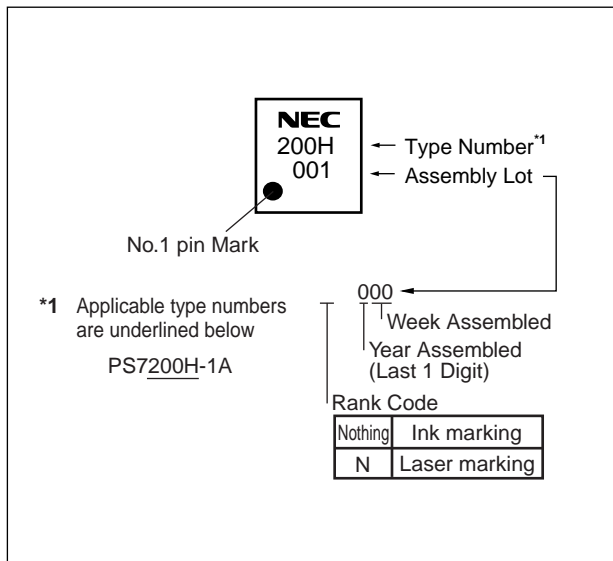
- Measurement equipment

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PACKAGE DIMENSIONS (UNIT: mm)



MARKING EXAMPLE



**ORDERING INFORMATION**

Part Number	Package	Packing Style	Application Part Number <sup>*1</sup>
PS7200H-1A	4-pin SOP	Magazine case 100 pcs	PS7200H-1A
PS7200H-1A-E3		Embossed Tape 900 pcs/reel	
PS7200H-1A-E4			
PS7200H-1A-F3		Embossed Tape 3 500 pcs/reel	
PS7200H-1A-F4			

\*1 For the application of the Safety Standard, following part number should be used.

**ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25°C, unless otherwise specified)**

Parameter		Symbol	Ratings	Unit
Diode	Forward Current (DC)	I <sub>F</sub>	50	mA
	Reverse Voltage	V <sub>R</sub>	5.0	V
	Power Dissipation	P <sub>D</sub>	50	mW
	Peak Forward Current <sup>*1</sup>	I <sub>FP</sub>	1	A
MOS FET	Break Down Voltage	V <sub>L</sub>	40	V
	Continuous Load Current	I <sub>L</sub>	160	mA
	Pulse Load Current <sup>*2</sup> (AC/DC Connection)	I <sub>LP</sub>	320	mA
	Power Dissipation	P <sub>D</sub>	100	mW
Isolation Voltage <sup>*3</sup>		BV	1 500	Vr.m.s.
Total Power Dissipation		P <sub>T</sub>	150	mW
Operating Ambient Temperature		T <sub>A</sub>	-40 to +85	°C
Storage Temperature		T <sub>stg</sub>	-40 to +100	°C

\*1 PW = 100 μs, Duty Cycle = 1%

\*2 PW = 100 ms, 1 shot

\*3 AC voltage for 1 minute at T<sub>A</sub> = 25°C, RH = 60% between input and output

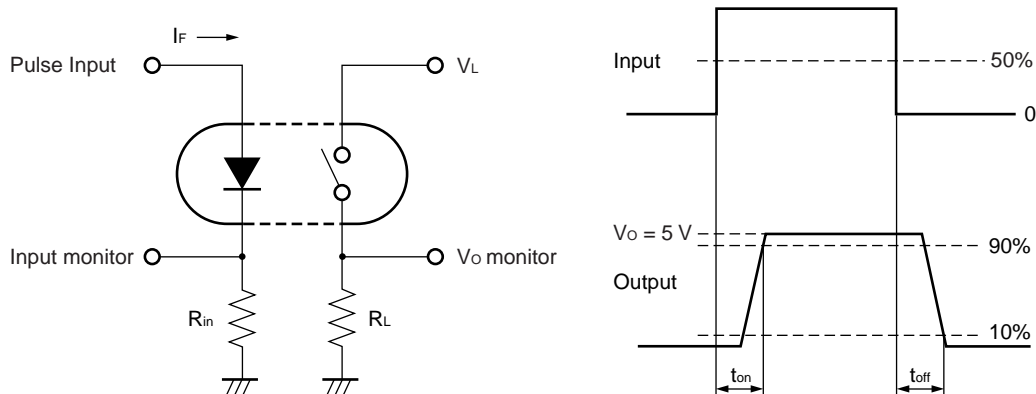
**RECOMMENDED OPERATING CONDITIONS (T<sub>A</sub> = 25°C)**

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
LED Operating Current	I <sub>F</sub>	2	10	20	mA
LED Off Voltage	V <sub>F</sub>	0		0.5	V

**ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25°C)**

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	V <sub>F</sub>	I <sub>F</sub> = 10 mA		1.2	1.4	V
	Reverse Current	I <sub>R</sub>	V <sub>R</sub> = 5 V			5.0	μA
MOS FET	Off-state Leakage Current	I <sub>Loff</sub>	V <sub>D</sub> = 40 V		0.03	10	nA
	Output Capacitance	C <sub>out</sub>	V <sub>D</sub> = 0 V, f = 1 MHz		4.2		pF
Coupled	LED On-state Current	I <sub>Fon</sub>	I <sub>L</sub> = 160 mA			2.0	mA
	On-state Resistance	R <sub>on1</sub>	I <sub>F</sub> = 10 mA, I <sub>L</sub> = 50 mA		2.2	3.5	Ω
		R <sub>on2</sub>	I <sub>F</sub> = 10 mA, I <sub>L</sub> = 160 mA, t ≤ 10 ms		2.2	3.5	
	Turn-on Time <sup>*1,2</sup>	t <sub>on</sub>	I <sub>F</sub> = 10 mA, V <sub>O</sub> = 5 V, R <sub>L</sub> = 500 Ω, PW ≥ 10 ms		0.04	0.5	ms
	Turn-off Time <sup>*1,2</sup>	t <sub>off</sub>			0.25	1.0	
	Isolation Resistance	R <sub>I-O</sub>	V <sub>I-O</sub> = 1.0 kV <sub>DC</sub>		10 <sup>9</sup>		Ω
	Isolation Capacitance	C <sub>I-O</sub>	V = 0 V, f = 1 MHz			0.4	pF

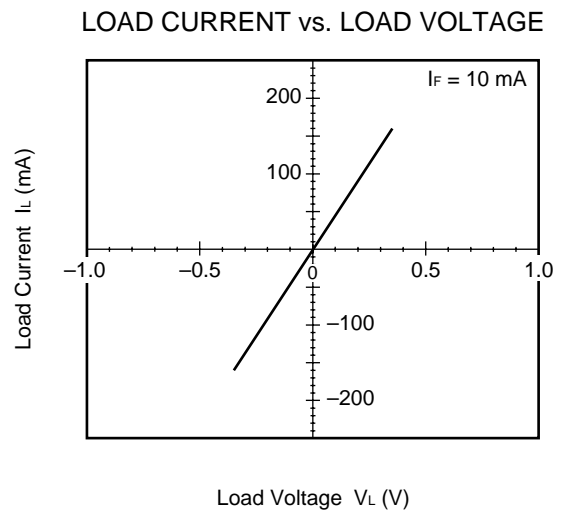
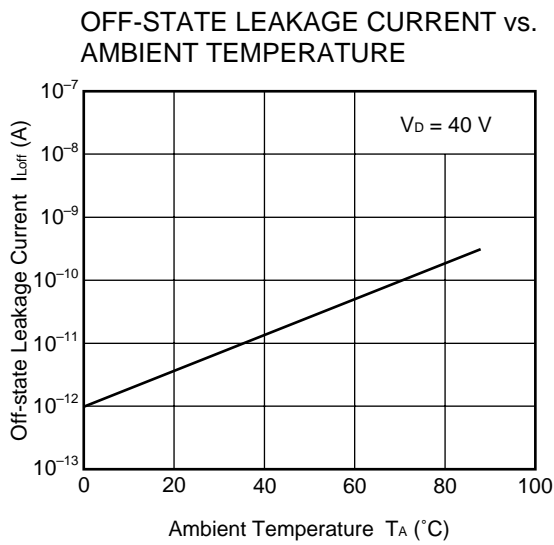
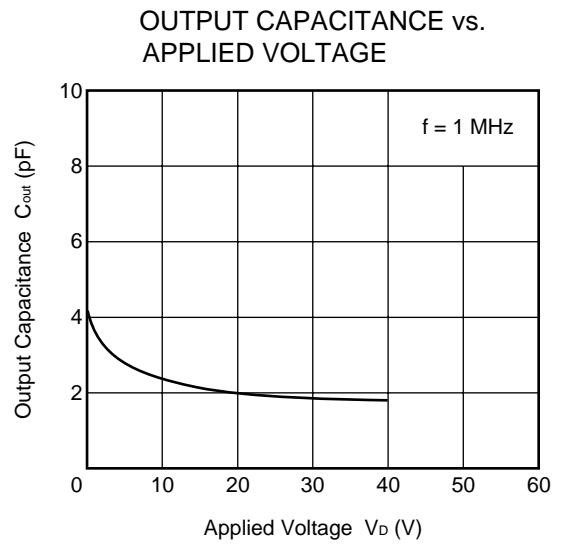
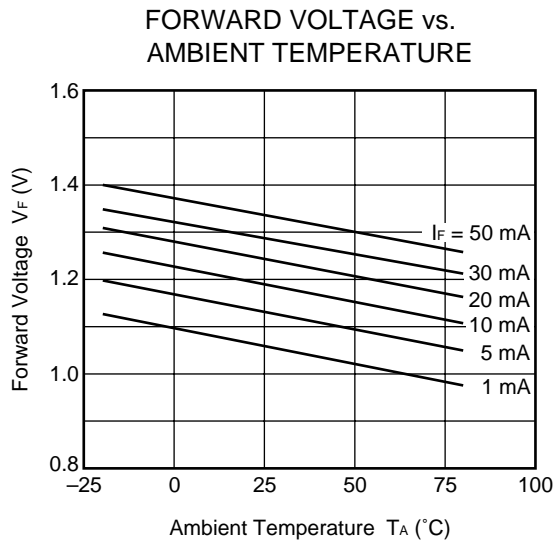
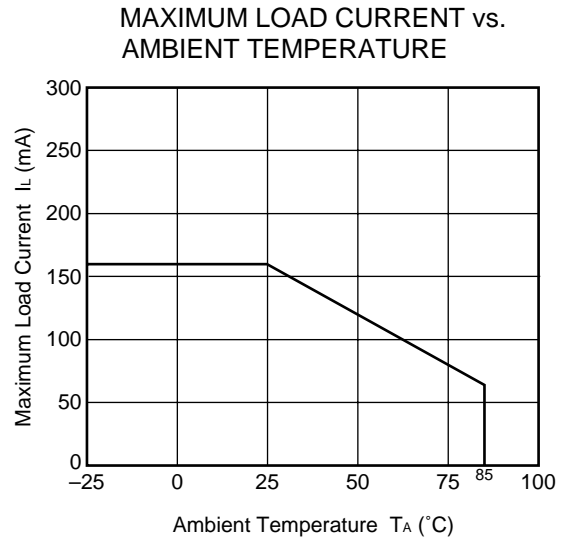
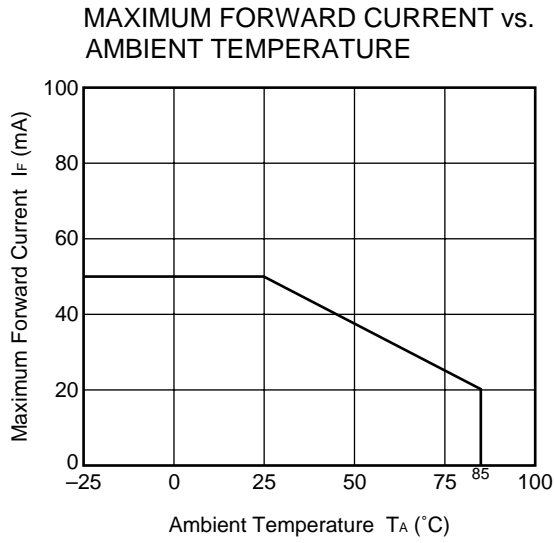
**\*1 Test Circuit for Switching Time**



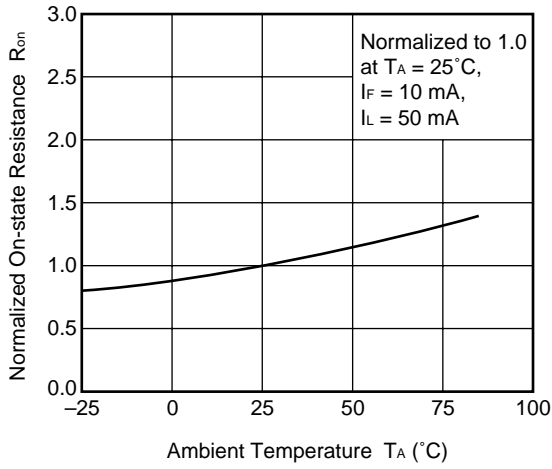
**\*2** The turn-on time and turn-off time are specified as input-pulse width ≥ 10 ms.

Be aware that when the device operates with an input-pulse width of under 10 ms, the turn-on time and turn-off time will increase.

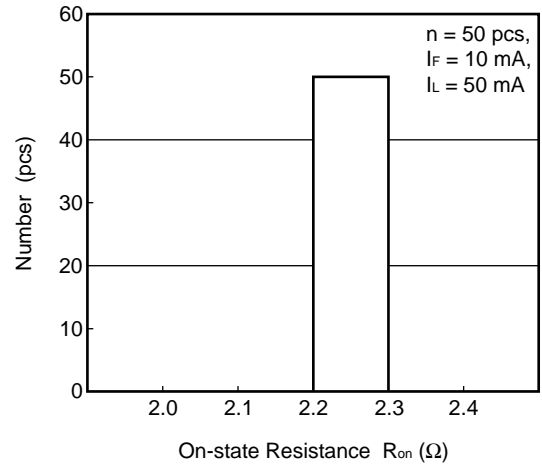
TYPICAL CHARACTERISTICS (T<sub>A</sub> = 25°C, unless otherwise specified)



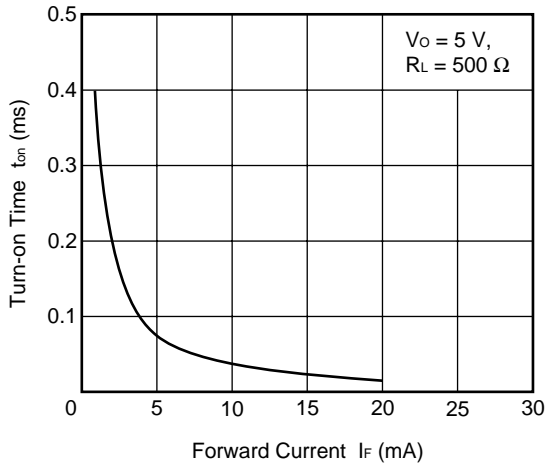
NORMALIZED ON-STATE RESISTANCE vs. AMBIENT TEMPERATURE



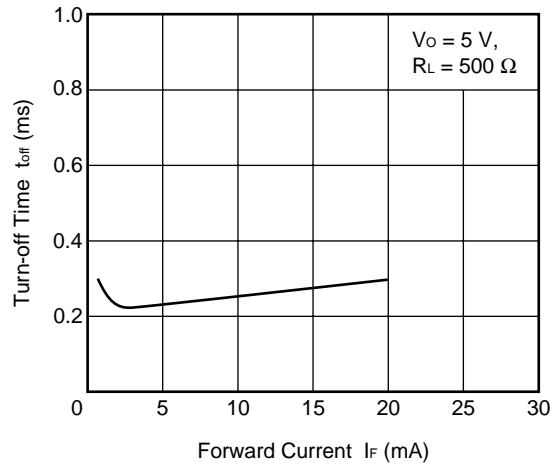
ON-STATE RESISTANCE DISTRIBUTION



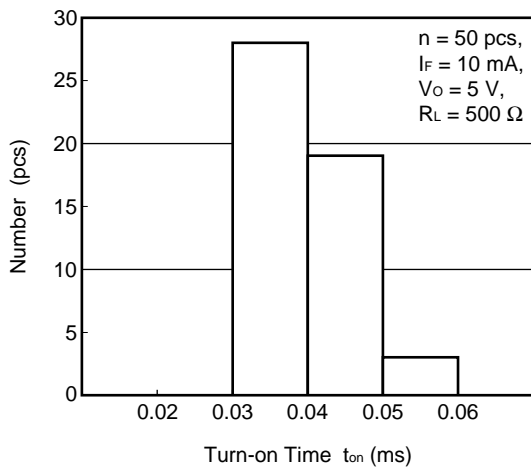
TURN-ON TIME vs. FORWARD CURRENT



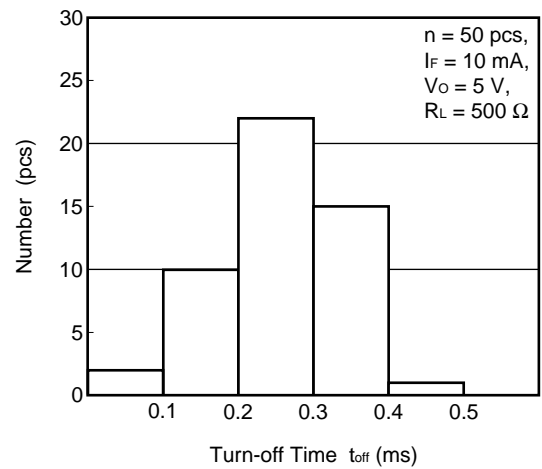
TURN-OFF TIME vs. FORWARD CURRENT



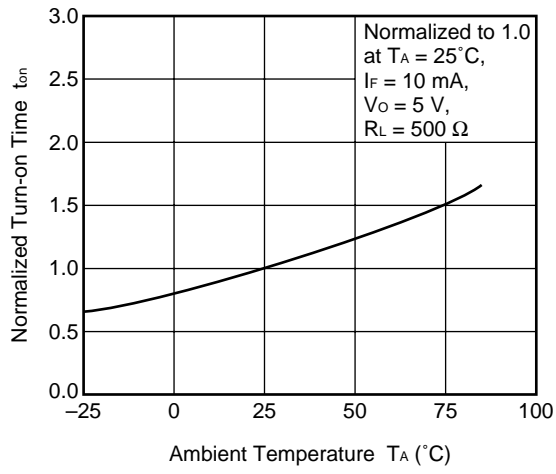
TURN-ON TIME DISTRIBUTION



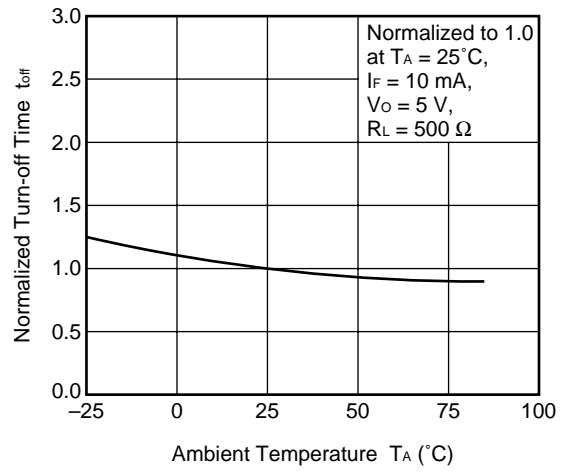
TURN-OFF TIME DISTRIBUTION



NORMALIZED TURN-ON TIME vs. AMBIENT TEMPERATURE



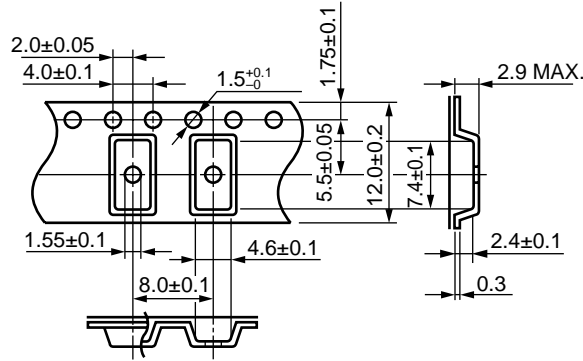
NORMALIZED TURN-OFF TIME vs. AMBIENT TEMPERATURE



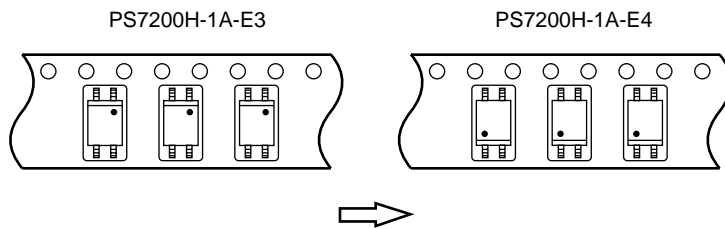
**Remark** The graphs indicate nominal characteristics.

★ TAPING SPECIFICATIONS (UNIT: mm)

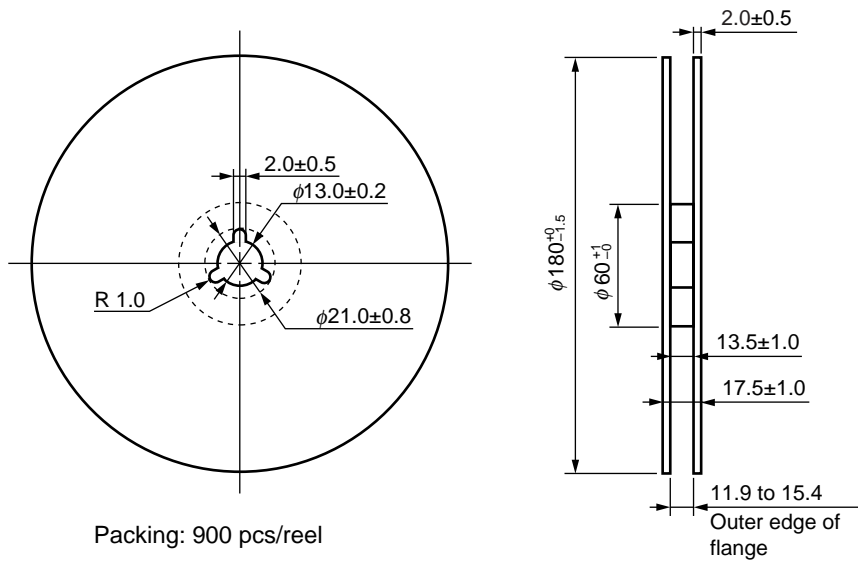
Outline and Dimensions (Tape)



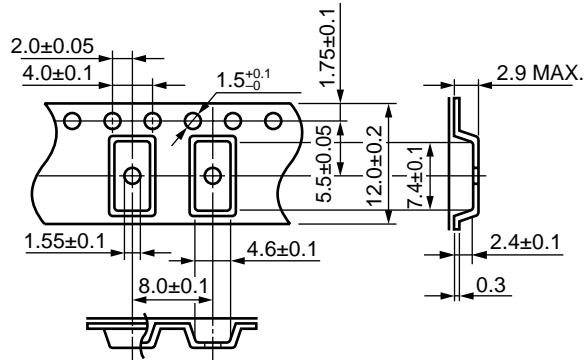
Tape Direction



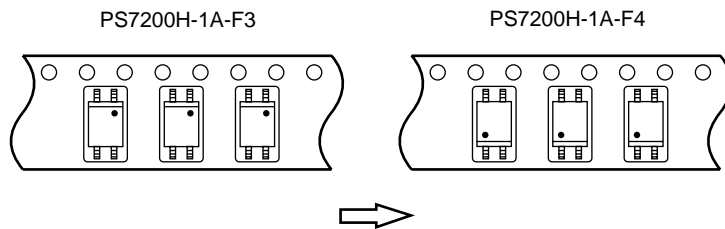
Outline and Dimensions (Reel)



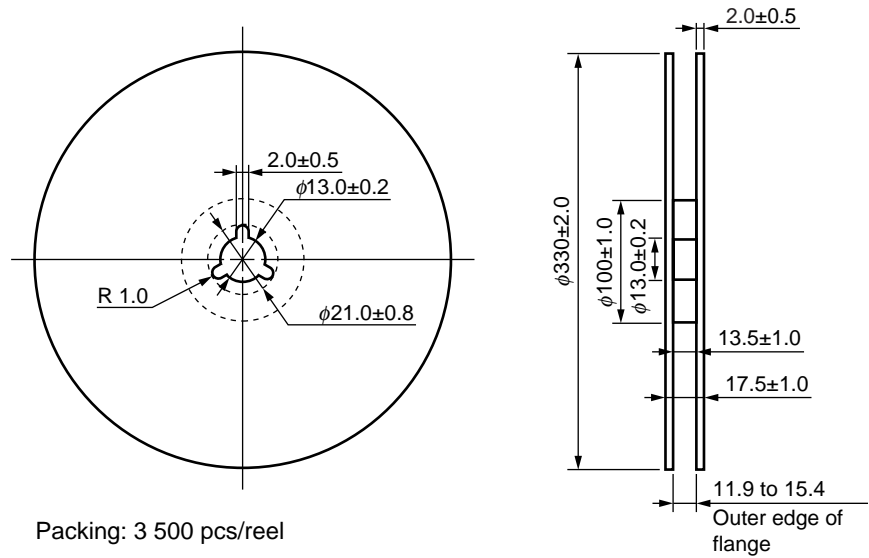
Outline and Dimensions (Tape)



Tape Direction



Outline and Dimensions (Reel)

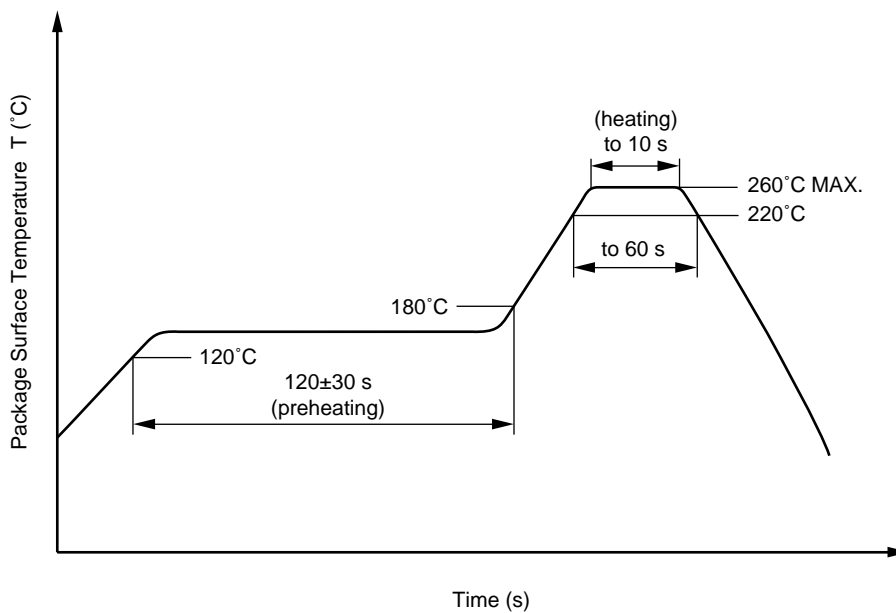


★ **RECOMMENDED SOLDERING CONDITIONS**

**(1) Infrared reflow soldering**

- Peak reflow temperature 260°C or below (package surface temperature)
- Time of peak reflow temperature 10 seconds or less
- Time of temperature higher than 220°C 60 seconds or less
- Time to preheat temperature from 120 to 180°C 120±30 s
- Number of reflows Three
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



**(2) Wave soldering**

- Temperature 260°C or below (molten solder temperature)
- Time 10 seconds or less
- Preheating conditions 120°C or below (package surface temperature)
- Number of times One
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

**(3) Cautions**

- Fluxes  
Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

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M8E 00.4-0110

**SAFETY INFORMATION ON THIS PRODUCT**

<p><b>Caution</b></p>	<p>GaAs Products</p>	<p>The product contains gallium arsenide, GaAs. GaAs vapor and powder are hazardous to human health if inhaled or ingested.</p> <ul style="list-style-type: none"> <li>• Do not destroy or burn the product.</li> <li>• Do not cut or cleave off any part of the product.</li> <li>• Do not crush or chemically dissolve the product.</li> <li>• Do not put the product in the mouth.</li> </ul> <p>Follow related laws and ordinances for disposal. The product should be excluded from general industrial waste or household garbage.</p>
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